



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of:

Azcarate, et al.

Serial No.: 09/392,899

Filed: 09/09/99

For: STRAPLESS LEAD FRAME

Docket No.: TI-22451

Examiner: Chambliss, A.

Art Unit: 2814

TECHNICAL

Amendment under 37 CFR 1.115

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the
U.S. Postal Service as First Class Mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231 on

9-25-01

Marianna Smith

Marianna Smith

Dear Sir:

The following amendments and remarks are offered in response to the
Examiner's Office Action dated 07/03/01. They are respectfully submitted as a
full and complete response to that Action.

Please amend the above-referenced application as follows:

In the Specification:

Please amend the specification as follows:

Paragraph at Page 4, line 11

The lead frame of FIG. 1a presents a greater problem in that the
semiconductor die to be mounted in the lead frame on die mount 12a is

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